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P. Walker
3-12-02

UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Fumihiko TANIGUCHI et al.**

Serial Number: **09/836,182**

Filed: **April 18, 2001**

Group Art Unit: **2822**

For: **METHOD OF FABRICATING SEMICONDUCTOR HAVING THROUGH HOLE** Examiner: **MITCHELL, J.**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
Washington, D.C. 20231

March 5, 2002

Sir:

In response to the Office Action dated December 10, 2001, please amend the above-identified application as follows:

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IN THE CLAIMS:

Please amend Claim 14, as follows:

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14. (Twice Amended) A semiconductor device comprising a semiconductor chip, a tape for mounting said semiconductor chip thereto, an adhesive resin layer interposed between said semiconductor chip and said tape, and solder balls arranged on said tape, characterized in that said tape is [made] of a material having high water permeability of $10 \text{ g/m}^2 \cdot 24\text{H}$ or more, sufficient to prevent cracking and bulging of said semiconductor device which might occur when the solder balls are reflowed after said semiconductor device absorbs moisture.

Please cancel Claim 15 without prejudice or disclaimer.